

EAST Search History

EAST Search History (Prior Art)

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
S10	6	((HANNES) near2 (HOFMANN)).INV.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/05/06 19:07
S20	73262	method with ((printed with cuitcuit with board) or (circuit with board) or pcb)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	OFF	2009/05/12 13:38
S21	27263	S20 and (vias or via or trench or recess)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	OFF	2009/05/12 13:39
S22	15426	S21 and (dielectric or insulat\$3)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/05/12 13:40
S23	620	S22 and (laser with ablation)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/05/12 13:40
S29	1072	laser with ((direct-write) or (direct write))	US-PGPUB; USPAT; USOCR	ADJ	ON	2009/05/12 17:30
S30	4	S29 with ((printed with cuitcuit with board) or (circuit with board) or pcb)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	OFF	2009/05/12 17:31
S34	4073	(circuit board) with coat\$3 with (dielectric or insulat\$3)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/05/12 18:45
S35	1	S34 with (puls\$3 with laser)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/05/12 18:45
S36	215	S34 and laser with (ablat\$3 or remov \$3)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/05/12 18:47
S38	91	laser with ((direct-write) or (direct write)) with (puls\$3 with laser)	US-PGPUB; USPAT; USOCR	ADJ	ON	2009/05/12 18:50
S47	73262	method with ((printed with cuitcuit with board) or (circuit with board) or pcb)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	OFF	2009/05/13 11:10
S49	50	S47 and (horizontal with technique)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	OFF	2009/05/13 11:11
S50	73262	method with ((printed with cuitcuit with board) or (circuit with board) or pcb)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	OFF	2009/05/13 11:30

S51	843	S50 and (horizontal with (technique or method))	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	OFF	2009/05/13 11:30
S52	117	S51 and (dip\$4)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	OFF	2009/05/13 11:30
S53	371	(205/80).CCLS.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/05/15 09:32
S57	3654	(428/209).CCLS.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/05/15 09:35
S60	247	S57 and laser with (ablat\$3 or remov \$3)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/05/15 09:37
S61	16	S60 and (via or vias) and (trench or recess)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	OFF	2009/05/15 09:37
S62	3705	(428/209).CCLS.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/11/02 09:44
S63	252	S62 and laser with (ablat\$3 or remov \$3)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/11/02 09:44
S64	76462	method with ((printed with cuitcuit with board) or (circuit with board) or pcb)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	OFF	2009/11/02 09:56
S65	879	S64 and (horizontal with (technique or method))	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	OFF	2009/11/02 09:56
S70	250429	"428"/\$.ccls.	US-PGPUB; USPAT; USOCR	ADJ	ON	2009/11/02 15:35
S71	12638	S70 AND S69	USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/11/02 15:36
S72	464	S71 and (pcb or printed circuit board)	USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/11/02 15:37
S73	252550	"428"/\$.ccls.	US-PGPUB; USPAT; USOCR	ADJ	ON	2010/01/11 18:25
S74	4673	S73 and (pcb or (print\$3 circuit board))	US-PGPUB; USPAT; USOCR	ADJ	ON	2010/01/11 18:27
S75	2838	S74 and @pd<"20040129"	US-PGPUB; USPAT; USOCR	ADJ	ON	2010/01/11 18:28
S76	7	S75 and (via or vias) and (trench or recess) and trace	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	OFF	2010/01/11 18:29

S79	8352	(29/830,831,832,852).OCLS.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2010/01/21 16:52
S80	47	S79 and (PCB or (print\$3 circuit board)) and traces and dielectric and (laser ablation)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2010/01/21 16:53
S83	91	S79 and (PCB or (print\$3 circuit board)) and ((copper or metal) adj layer) and dielectric and (laser ablation)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2010/01/21 17:51
S85	70	((MARK) near2 (MCCORMACK)).INV.	US-PGPUB; USPAT; USOCR	ADJ	ON	2010/01/21 17:59
S86	31	(high density interconnection) and (PCB or (print\$3 circuit board)) and ((copper or metal) adj layer) and dielectric and (laser ablation)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2010/01/21 18:29
S87	49	(high density interconnection) and ((copper or metal) adj layer) and dielectric and (laser ablation)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2010/01/21 18:48
S89	8586	(29/830,831,832,852).OCLS.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2010/06/18 18:53
S90	97	S89 and (PCB or (print\$3 circuit board)) and ((copper or metal) adj layer) and dielectric and (laser ablation)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2010/06/18 18:53
S96	35	((REINHARD) near2 (SCHNEIDER)).INV.	US-PGPUB; USPAT; USOCR	ADJ	ON	2010/06/18 20:04
S97	30	((DAVID) near2 (BARON)).INV.	US-PGPUB; USPAT; USOCR	ADJ	ON	2010/06/18 20:06
S98	3651	(29/846).OCLS.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2010/06/18 20:38
S103	4845	(257/40).OCLS.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2010/06/19 10:15
S104	259	S103 and ((printed with cuitcuit with board) or (circuit with board) or pcb)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	OFF	2010/06/19 10:16
S105	3651	(29/846).OCLS.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2010/06/19 10:52
S106	1976	S105 and ((printed with cuitcuit with board) or (circuit with board) or pcb)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	OFF	2010/06/19 10:52
S107	323	S106 and (laser with (ablat\$3 or remov \$3))	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2010/06/19 10:53
S108	208	S106 and (laser with (ablat\$3 or remov \$3)) and @ay< "2005"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2010/06/19 10:53

S111	14	"29"/\$.ccls. and (vias with V-shape)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2010/06/19 14:34
S112	8586	(29/830,831,832,852).OCLS.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2010/06/19 14:35
S114	3	"428"/\$.ccls. and (vias with V-shape)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2010/06/19 14:37
S115	3	"428"/\$.ccls. and ((vias or trench or trace) with V-shape)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2010/06/19 14:37
S116	3651	(29/846).OCLS.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2010/06/19 14:38
S118	3	S116 and ((vias or trench or trace) with V near shape)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2010/06/19 14:38
S119	65	((printed with cuitcuit with board) or (circuit with board) or pcb) and ((vias or trench or trace) with V near shape)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2010/06/19 14:49

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